

Abstract

385

Electronic Module, in Particular a Multichip Module, Comprising a Multilayer Wiring and Method of Making the Same

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The component side of the multilayer wiring (2) adheres with its component-free portions to the hermetic case (4), and the bottom side of the multilayer wiring (2) having a height of less than approx. 100 μm , directly, 395 i.e. without additional wiring substrate (1), constitutes the bottom side of the module.

Figure 1